



## HE-B73 - Half-size PICMG 1.3

The HE-B73, designed for the 11th generation Intel® Core™ H-series processor platform, provides excellent CPU, graphics, media performance, flexibility, and enhanced security ideally suited to applications requiring multi-tasking capabilities, such as gaming, surveillance, medical, defense, transportation and industrial automation application.

## **SPECIFICATIONS**

CPU 11th Gen Intel® Tiger Lake

CPU Socket FCBGA1787

Memory Type 260-pin DDR4 3200 MHz SO-DIMM

Memory Slots 2

**Maximum Memory Supported** 64GB

Chipset QM580E / RM590E (TGL-H Xeon CPUs have to use RM590E)

Integrated Graphics Intel® UHD Graphics

**Watchdog Timer** 1 ~ 255 min/sec intervals, generates system reset

Serial ATA (SATA) 2 x SATA III

Video 1 x DVI (see Note), 1 x VGA, 1 x LVDS (see Note) & 1 x DP (see Note)

 $1 \times Intel \$ \ 1219-LM \ Gigabit \ LAN \ (Support \ Intel \$ \ AMT \ 15.0), \ 1 \times Intel \$ \ 1225-LM \ LAN \ Ports$ 

Gigabit LAN (Up to 2.5GbE)

**GPIO Interface** 1 x GPIO

**Extended Interface** 1 x Mini-PCle/mSATA, 1 x M.2 2230 E-Key, 1 x M.2 2280 M-Key PCle Gen 4

1 x PCle X16 slot via backplane, 1 x PCle X4 or 4 x PCle X1 via backplane (see

Expansion Interface ordering options)

2 x SATA3, 4 x RS232, 2 x RS232/RS422/RS485, 1 x SMBus, 2 x USB 3.2 (Type

Internal I/O

E), 4 x USB 2.0, 1 x LVDS, 1 x LCD inverter connector

**Rear I/O** 2 x LAN, 1 x DisplayPort and 1 x PS/2

Audio Realtek ALC888S HD Audio

**Power Requirement** 24-pin ATX power from Backplane

**Dimensions** 168 mm x 126 mm

**Operating Temperature**  $0 \sim 60^{\circ}\text{C} (32 \sim 140^{\circ}\text{F}) \text{ (Wide Temp Version option is -40 <math>\sim 85^{\circ}\text{C})}$ 

**Storage Temperature**  $-20 \sim 80 \,^{\circ}\text{C} \, (-4 \sim 176 \,^{\circ}\text{F})$ 

**Relative Humidity** 10 ~ 90% (non-condensing)

OS Software Supported Windows 10 64bit

Global P/N / SKU 3308586

## **ORDERING OPTIONS**

HE-B7371 - With Core<sup>™</sup> i7-11850HE, QM580E, Cooler fan, DVI, DP, LVDS, VGA, 4 x PCle X1 HE-B7374 - Same as HE-B7371, with 1 x PCle X4 M2-3502 - M2 2280 M-Key supporting 2 x Gigabit LAN M2-3504 - M2 2280 M-Key supporting 4 x Gigabit LAN HE-B7351- With Core<sup>™</sup> i5-11500HE, QM580E, Cooler fan, DVI, DP, LVDS, VGA, 4 x PCle X1 HE-B7331 - With Core<sup>™</sup> i3-11100HE, QM580E, Cooler fan, DVI, DP, LVDS, VGA, 4 x PCle X1 HE-B73C1 - With Celeron® 6600HE, QM580E, Cooler fan, DVI, DP, LVDS, VGA, 4 x PCle X1 HE-B73W7R1 - With Xeon® W-11865MRE, RM590E, Cooler fan, DVI, DP, LVDS, VGA, 4 x PCle X1 Other Xeon Processors Options and Boards with 1 x PCle X4 instead are available. Please ask Sales Rep for further assistance. **Note1** (LVDS): Onboard 18/24-bit single/dual channel +3.3V/ +5V/ +12V LVDS **Note2** (Additional VGA or 2nd LVDS): Add ADP-3355 supports 2nd VGA or Add ADP-3460 supports 2nd LVDS, please contact with our sales for OEM version **Note3**: W-11865MRE, W-11555MRE, W-11155MRE can operate within -40°C ~ 85°C **Note4**: If you want to use other Tiger Lake /11th Gen H Processor , please ask Sales Rep for further assistance. **Note5** (**DVI**): DVI Cable is optional.